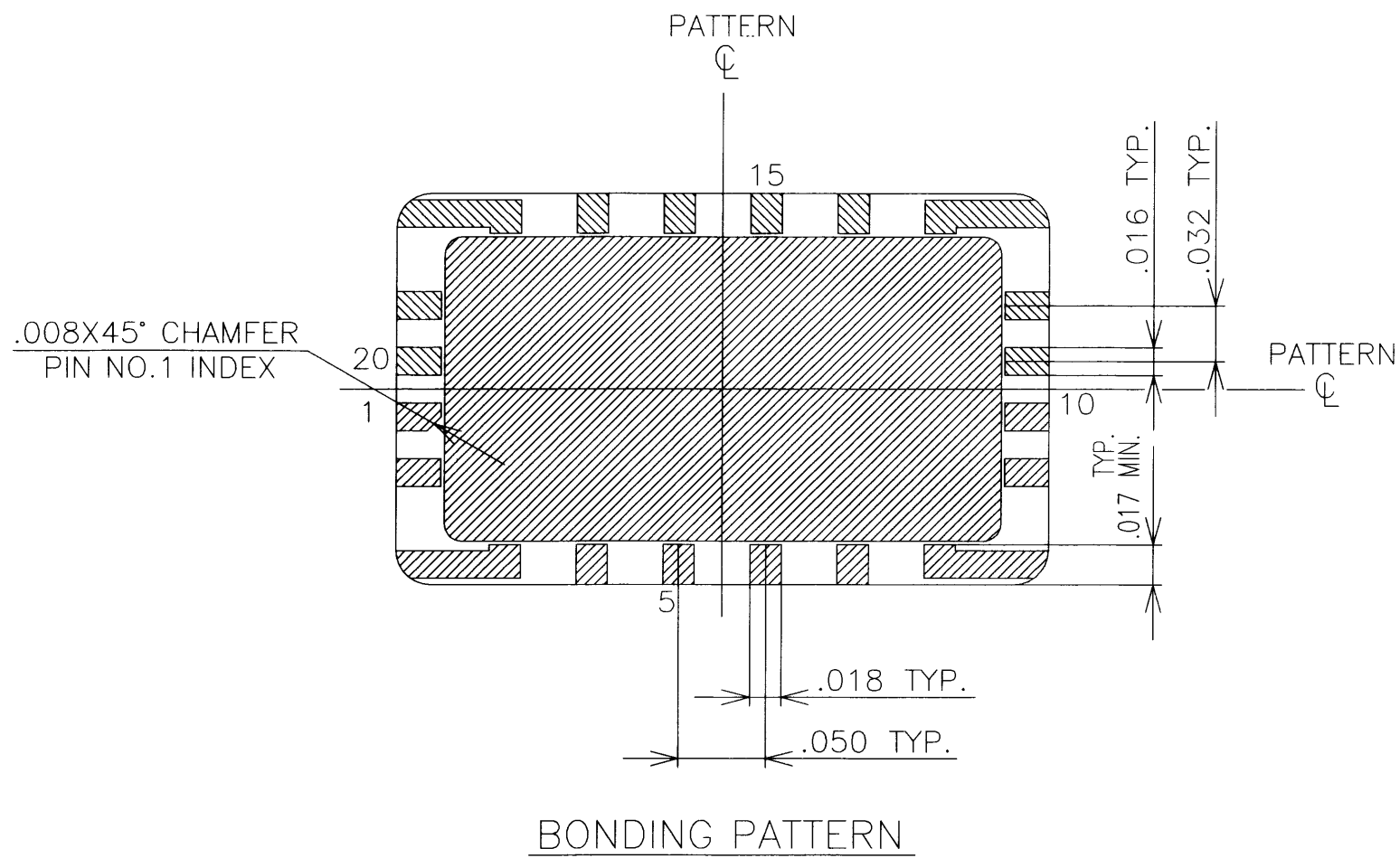


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.30 OHM MAX.

SB020S832-1 S=0 D=0

MODIFICATION					NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN Y.M	CHECKED K.O	APPROVED K.M	DATE SEP.20.'86
					SCALE 5 / 1	MATERIAL AS INDICATED	<i>Y. Matsui</i>	<i>K. Ota</i>	<i>H. Sako</i>	
						KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S86832		SHEET 1 / 2	
		CHANGED	DATE	DRAWN	CHECKED	APPROVED				



MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					20 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.M	K.O	K.M	SEP.20.'86
				SCALE 10 / 1	MATERIAL					
						THIRD ANGLE PROJECTION	<i>Y. Matsui</i>	<i>Y. Kojima</i>	<i>H. Sako</i>	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S86832		SHEET 2 / 2	